

REV.	ECN.NO.	APPD.
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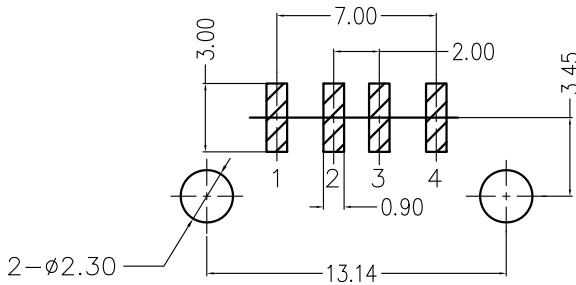
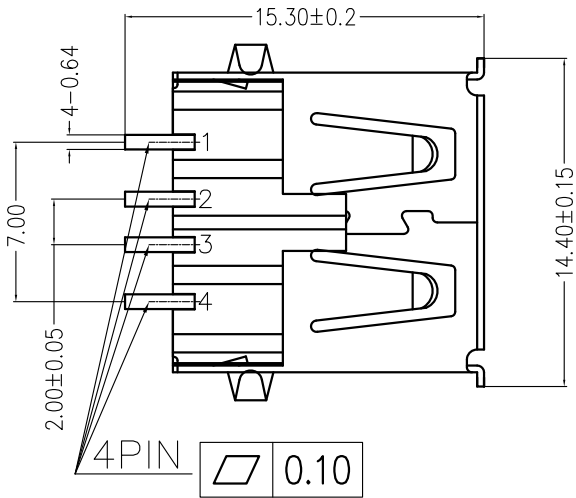
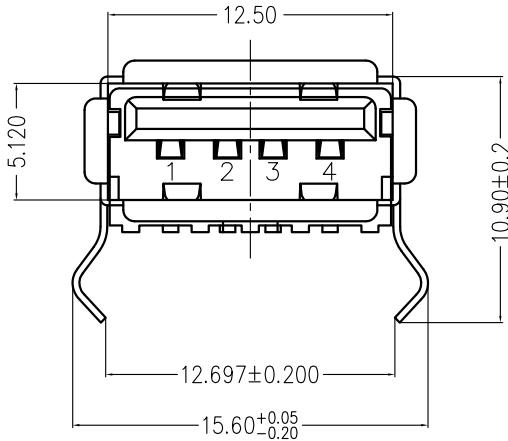
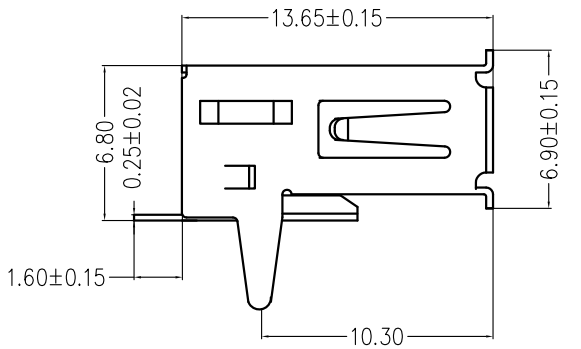
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PCB.LAYOUT

- NOTES:
- 1.MATERIAL:
 - 1.1 Housing:thermoplastic plastics
 - 1.2 terminals:Copper Alloy
 - Gold plated in contact area:
 - Tin plated in termination
 - Nickel Plated overall
 - 1.3 Shell:Steel&Copper Alloy
 - Nickel Plated overall
 - 2.ELECTRICAL CHARACTERISTICS:
 - 2.1 Rating Current :1.5 Ampere
 - 2.2 Rating Voltage :30 V Max
 - 2.3 Contact Resistance:30 Milli ohms
 - 2.4 Insulation Resistance:1000 Mega ohms Min.
 - 3.MECHANICAL CHARACTERISTICS:
 - 3.1 Connector Mating force: 35N MAX(3.57Kgf)
 - 3.2 Connector Unmating force:10N min(1.02Kgf)
 - 3.3 Durability:1500Cycles.
 - 4.ENVIRONMENT CHARACTERISTICS:
 - 4.1 Operating temperature:-0℃ to +50℃
 - 4.2 Storage temperature:-20℃ to +60℃

U222-0321-G63018

1:铁壳镀镍

G:半金G/F

6:LCP

1:吸塑盒

3:米黄色

TOLERANCE UNLESS OTHERWISE SPECIFIED		HLW 深圳市华联威电子科技有限公司					
.XXX ±0.10	.X" ±3'	HUA LIAN WEI TECHNOLOGY ELECTRONICS CO;LTD.					
.XX ±0.20	.X" ±2'						
.X ±0.30	.X" ±2'						
APPROVED		PART NAME:	USB AF T型 SMT 弯脚无盖				
CHECKED		PART No:	U222-0321-G63018			C	
DRAWN	chenyiting	PROJECTION:	UNIT:	SCALE	SHEET	REV.	
DATE	2022. 10. 09		mm	1:1	10F1	A0	